

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L6 | 6 | ("5844782" "5874782" "5925931" "6211572" "6284563").PN. OR ("6835595").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/30 10:04 |
| L9 | 6 | ("5602422" "5943597" "6028364" "6064576" "6394819" "6503777").PN. OR ("6806570").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/30 10:07 |
| L11 | 11 | ("3832632" "5329423" "5342207" "5378982" "5415555" "5434513" "5489804" "5508228" "5764209").PN. OR ("6552563").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/30 10:09 |
| L25 | 284 | @ad<="20031230" and solder same bond\$3 with pad same (relief or compliant) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 10:24 |
| L28 | 389 | @ad<="20031230" and solder same bond\$3 with pad with flexible | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 10:28 |
| L29 | 47 | @ad<="20031230" and solder same bond\$3 with pad with compliant | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 10:29 |
| L30 | 692 | @ad<="20031230" and pad with modulus and low | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 10:45 |
| L31 | 111 | @ad<="20031230" and pad with "low modulus" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 10:31 |
| L32 | 22 | ("4999460" "5001302").PN. OR ("5666270").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/30 10:32 |
| L33 | 100 | @ad<="20031230" and contact\$3 with pad with modulus | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 10:45 |
| L34 | 119 | @ad<="20031230" and bond\$3 with pad with modulus | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 10:46 |

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|-----|------|---|---|----|----|------------------|
| L35 | 995 | @ad<="20031230" and pad with modulus | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 11:15 |
| L36 | 22 | @ad<="20031230" and flexible with pad with modulus | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 11:16 |
| S1 | 9 | ("5796163" "6201305" "6586676" "6624504").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 16:09 |
| S2 | 6859 | @ad<="20031230" and (257/668).ccls. or (257/737-738).ccls. or (257/780-781).ccls. or (257/E21.503).ccls. or (257/E23.119).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:34 |
| S3 | 5226 | @ad<="20031230" and (257/734).ccls. or (257/784).ccls. or (257/779).ccls. or (257/786).ccls. or (257/792).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 12:17 |
| S4 | 1 | @ad<="20031230" and (257/668).ccls. and 'solder contact' same 'pad' same 'flexible' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 14:24 |
| S5 | 1 | @ad<="20031230" and (257/668).ccls. and 'bonding pad' same 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 13:37 |
| S6 | 44 | @ad<="20031230" and (257/668).ccls. and 'bonding pad' same 'flexible' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 13:41 |
| S7 | 3 | @ad<="20031230" and (257/668).ccls. and 'bonding pad' same 'compliant layer' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/04 08:57 |
| S8 | 1 | "6147401".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:45 |
| S9 | 1 | "6043563".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:47 |
| S10 | 1 | "5885849".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:48 |
| S11 | 1 | "4736236".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:52 |

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|-----|-----|---|---|----|----|------------------|
| S12 | 1 | "4670770".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:52 |
| S13 | 1 | "4612566".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:53 |
| S14 | 1 | "4527330".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:53 |
| S15 | 1 | "4413308".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:53 |
| S16 | 1 | "4232512".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:54 |
| S17 | 1 | "4215359".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:56 |
| S18 | 1 | "4200975".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:56 |
| S19 | 4 | @ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:05 |
| S20 | 1 | "6147401".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:58 |
| S21 | 1 | "6043563".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:58 |
| S22 | 1 | "5929517".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:58 |
| S23 | 1 | "5885849".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:59 |
| S24 | 1 | "5749997".PN. | USPAT; USOCR | OR | ON | 2005/02/03 13:59 |
| S25 | 1 | "5679977".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:00 |
| S26 | 1 | "5666270".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:01 |
| S27 | 1 | "5180311".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:02 |
| S28 | 1 | @ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'Resilient' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:08 |
| S29 | 3 | @ad<="20031230" and (257/668). ccls. and 'pad' same 'compliance' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:09 |
| S30 | 111 | @ad<="20031230" and 'bonding pad' same 'Resilient' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:09 |

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|-----|------|--|---|----|----|------------------|
| S31 | 12 | @ad<="20031230" and 'bonding pad' same 'Resilience' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:09 |
| S33 | 30 | @ad<="20031230" and (257/668). ccls. and 'pad' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:04 |
| S34 | 44 | @ad<="20031230" and 'bonding pad' same 'compliance' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:10 |
| S35 | 136 | @ad<="20031230" and 'bonding pad' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:10 |
| S36 | 3 | @ad<="20031230" and 'solder contact' same 'pad' same 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:11 |
| S37 | 919 | @ad<="20031230" and 'pad' with 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 10:59 |
| S38 | 11 | @ad<="20031230" and 'solder' and 'pad' with 'different' with 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:13 |
| S39 | 3685 | @ad<="20031230" and (257/668). ccls. or (257/737-738).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 14:34 |
| S40 | 1 | "6049130".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:35 |
| S41 | 1 | "6034431".PN. | USPAT; USOCR | OR | ON | 2005/02/03 14:36 |
| S42 | 570 | @ad<="20031230" and 'compliant contact' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:05 |
| S43 | 74 | @ad<="20031230" and 'solder ball' and 'compliant contact' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:05 |

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|-----|-----|---|---|----|-----|------------------|
| S44 | 1 | "6333563".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:18 |
| S45 | 1 | "6221697".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:19 |
| S46 | 1 | "6443351".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:22 |
| S47 | 1 | "6409073".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:23 |
| S48 | 1 | "6396156".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:23 |
| S49 | 1 | "6369451".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:24 |
| S50 | 1 | "6333104".PN. | USPAT; USOCR | OR | ON | 2005/02/03 15:24 |
| S51 | 20 | @ad<="20031230" and 'bonding pad' with 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:44 |
| S53 | 219 | @ad<="20031230" and 'bonding pad' and 'solder ball' and 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:45 |
| S54 | 81 | @ad<="20031230" and 'bonding pad' and 'solder ball' and 'compliant layer' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/03 15:45 |
| S55 | 11 | ((("6333559") or ("6376279") or ("6541844") or ("6465867") or ("6204165"))).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/02/04 08:49 |
| S56 | 2 | ("6211572").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/02/04 08:49 |
| S57 | 1 | "5874782".PN. | USPAT; USOCR | OR | ON | 2005/02/04 08:50 |
| S58 | 1 | "5777379".PN. | USPAT; USOCR | OR | ON | 2005/02/04 08:52 |
| S59 | 1 | "5679977".PN. | USPAT; USOCR | OR | ON | 2005/02/04 08:57 |
| S61 | 233 | @ad<="20031230" and 'compliant' with 'packaging' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/04 08:58 |

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| S62 | 92 | @ad<="20031230" and 'bonding pad' and 'compliant' with 'package' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/04 08:59 |
| S63 | 2 | @ad<="20031230" and 'bonding pad' same 'compliant' with 'packaging' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/02/04 08:59 |
| S64 | 1 | "5001302".PN. | USPAT; USOCR | OR | ON | 2005/06/17 14:23 |
| S69 | 1 | "5777379".PN. | USPAT; USOCR | OR | ON | 2005/06/17 14:36 |
| S70 | 1 | "5677576".PN. | USPAT; USOCR | OR | ON | 2005/06/17 14:36 |
| S73 | 1 | "6333565".PN. | USPAT; USOCR | OR | ON | 2005/06/17 15:18 |
| S74 | 1 | "6277669".PN. | USPAT; USOCR | OR | ON | 2005/06/17 15:21 |
| S75 | 117 | @ad<="20031230" and 'solder ball' same 'contact pad' same 'flexible' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 16:04 |
| S76 | 570 | @ad<="20031230" and 'solder ball' and 'contact pad' and 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 15:23 |
| S77 | 607 | @ad<="20031230" and 'contact pad' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 15:23 |
| S78 | 1289 | @ad<="20031230" and 'contact pad' same 'resilient' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 15:23 |
| S79 | 13 | @ad<="20031230" and 'solder ball' with 'contact pad' same 'resilient' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 15:43 |
| S80 | 18 | @ad<="20031230" and 'solder ball' with 'contact pad' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 15:45 |

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| S81 | 1543 | @ad<="20031230" and 'pad' same 'contact' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 15:24 |
| S82 | 8 | @ad<="20031230" and 'solder ball' same 'contact pad' with 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 15:25 |
| S83 | 77 | @ad<="20031230" and 'solder ball' and 'contact pad' with 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 16:18 |
| S84 | 1 | "5956235".PN. | USPAT; USOCR | OR | ON | 2005/06/17 15:32 |
| S85 | 1 | "5868304".PN. | USPAT; USOCR | OR | ON | 2005/06/17 15:32 |
| S86 | 81 | @ad<="20031230" and 'solder ball' and 'contact pad' with 'resilient' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 15:43 |
| S87 | 8 | @ad<="20031230" and 'solder ball' same 'contact pad' with 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 15:45 |
| S89 | 739 | @ad<="20031230" and 'contact pad' with 'resilient' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 16:05 |
| S90 | 302 | @ad<="20031230" and 'contact pad' with 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 16:12 |
| S91 | 57 | @ad<="20031230" and 'bonding pad' with 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 16:12 |
| S92 | 58 | @ad<="20031230" and 'bonding pad' with 'resilient' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 16:12 |
| S93 | 576 | @ad<="20031230" and 'bonding pad' with 'flexible' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 16:12 |

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| S94 | 1 | "6147401".PN. | USPAT; USOCR | OR | ON | 2005/06/17 16:14 |
| S95 | 1 | "6043563".PN. | USPAT; USOCR | OR | ON | 2005/06/17 16:14 |
| S97 | 1086 | @ad<="20031230" and 'compliant' and 'solder balls' and 'pad' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/27 08:37 |
| S99 | 70 | @ad<="20031230" and 'compliant' and 'solder balls' and 'copper' and 'TCE' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 17:22 |
| S10 0 | 1 | "6503777".PN. | USPAT; USOCR | OR | ON | 2005/06/27 08:41 |
| S10 1 | 1 | "6394819".PN. | USPAT; USOCR | OR | ON | 2005/06/27 08:41 |
| S10 2 | 6 | ((("5943597") or ("6028364") or ("6394819"))).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/17 16:10 |
| S10 3 | 3 | ("6806570").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/17 16:15 |
| S10 4 | 1 | "6503777".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:15 |
| S10 5 | 1 | "6394819".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:15 |
| S10 6 | 1 | "6064576".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:16 |
| S10 7 | 1 | "6028364".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:16 |
| S10 8 | 1 | "5602422".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:16 |
| S10 9 | 2 | ("6720212").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/17 16:17 |
| S11 0 | 9 | @ad<="20031230" and 'solder ball' same 'contact pad' with 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 16:21 |

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| S11 1 | 41 | @ad<="20031230" and 'contact pad' with 'compliant layer' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 16:21 |
| S11 2 | 184 | @ad<="20031230" and 'pad' with 'compliant layer' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 16:22 |
| S11 3 | 302 | @ad<="20031230" and 'pad' with 'compliant material' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/18 08:12 |
| S11 4 | 74 | @ad<="20031230" and 'solder' and 'pad' with 'compliant material' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 16:44 |
| S11 5 | 1 | "6743660".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:28 |
| S11 6 | 1 | "6433427".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:28 |
| S11 7 | 1 | "6235552".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:30 |
| S11 8 | 1 | "6277669".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:31 |
| S11 9 | 1 | "6197613".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:32 |
| S12 0 | 1 | "6187680".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:33 |
| S12 1 | 1 | "6187615".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:33 |
| S12 2 | 1 | "6163463".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:34 |
| S12 3 | 1 | "6235552".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:34 |
| S12 4 | 1 | "6071755".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:34 |
| S12 5 | 1 | "5851911".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:35 |
| S12 6 | 1 | "5969424".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:35 |
| S12 7 | 1 | "6033939".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:36 |
| S12 8 | 1 | "6037044".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:36 |

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| S12 9 | 210 | @ad<="20031230" and 'solder' and 'bonding pad' with 'stress' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 16:44 |
| S13 0 | 71 | @ad<="20031230" and 'solder' same 'bonding pad' with 'stress' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 16:54 |
| S13 1 | 30 | @ad<="20031230" and 'solder' same 'bonding pad' same 'compliant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 17:32 |
| S13 2 | 1 | "6838368".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:55 |
| S13 3 | 1 | "6809020".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:55 |
| S13 4 | 1 | "6413845".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:56 |
| S13 5 | 1 | "6125043".PN. | USPAT; USOCR | OR | ON | 2005/10/17 16:56 |
| S13 6 | 72 | @ad<="20031230" and 'compliant' and 'solder balls' and 'copper' and 'TCE' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 17:00 |
| S13 7 | 1 | "20020089058".PN. | US-PGPUB | OR | ON | 2005/10/17 17:02 |
| S13 8 | 1 | "6638870".PN. | USPAT; USOCR | OR | ON | 2005/10/17 17:02 |
| S13 9 | 1 | "6337445".PN. | USPAT; USOCR | OR | ON | 2005/10/17 17:03 |
| S14 0 | 1 | "6147401".PN. | USPAT; USOCR | OR | ON | 2005/10/17 17:04 |
| S14 1 | 22 | @ad<="20031230" and 'bonding pad' with 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 17:12 |
| S14 2 | 28 | @ad<="20031230" and 'bond pad' with 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 17:12 |
| S14 3 | 191 | @ad<="20031230" and 'stress buffer' and ('ball' or 'bump') and 'pad' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/17 17:23 |

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| S14 4 | 38 | @ad<="20031230" and 'stress buffer' and ('ball' or 'bump') and 'pad' and 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 13:54 |
| S14 5 | 1 | "6743660".PN. | USPAT; USOCR | OR | ON | 2005/10/17 17:29 |
| S14 6 | 1 | "6433427".PN. | USPAT; USOCR | OR | ON | 2005/10/17 17:30 |
| S14 7 | 1 | "6277669".PN. | USPAT; USOCR | OR | ON | 2005/10/17 17:30 |
| S14 8 | 1 | "6235552".PN. | USPAT; USOCR | OR | ON | 2005/10/17 17:30 |
| S14 9 | 1 | "6189208".PN. | USPAT; USOCR | OR | ON | 2005/10/17 17:31 |
| S15 0 | 93 | @ad<="20031230" and 'solder ball' and 'compliant pad' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/18 08:23 |
| S15 1 | 20 | @ad<="20031230" and 'solder ball' same 'compliant pad' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/18 08:13 |
| S15 3 | 1230 | @ad<="20031230" and 'solder ball' and ('compliant' or 'stress') with 'pad' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/18 08:25 |
| S15 4 | 342 | @ad<="20031230" and 'solder ball' and 'compliant' with 'pad' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/18 08:25 |
| S15 5 | 25 | @ad<="20031230" and 'solder ball' and 'compliant' with 'bonding pad' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/18 08:39 |
| S15 6 | 307 | @ad<="20031230" and 'young modulus' with 'copper' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/18 08:45 |
| S15 7 | 307 | @ad<="20031230" and 'copper' with 'young' adj1 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/18 09:19 |

EAST Search History

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| S15 8 | 13 | @ad<="20031230" and 'compliant material' same 'polymer' same 'dielectric' same 'metal' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/18 10:12 |
| S15 9 | 2 | ("5148266").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/18 10:12 |
| S16 2 | 688 | @ad<="20031230" and ('stress buffer' or 'compliant') and ('ball' or 'bump') and 'pad' and 'modulus' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/09 11:48 |
| S16 3 | 18 | ((("6806570") or ("6255737") or ("6900548") or ("6624504") or ("6770547") or ("6946723") or ("6835595") or ("6835595")).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/04/18 12:12 |
| S16 4 | 1 | "6284563".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:30 |
| S16 5 | 1 | "6211572".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:30 |
| S16 6 | 1 | "5925931".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:30 |
| S16 7 | 1 | "5874782".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:30 |
| S16 8 | 1 | "5844782".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:31 |
| S16 9 | 1 | "20020076651".PN. | US-PGPUB | OR | ON | 2006/04/18 13:35 |
| S17 0 | 1 | "6472724".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:35 |
| S17 1 | 1 | "6472249".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:35 |
| S17 2 | 1 | "6313532".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:35 |
| S17 3 | 1 | "6287893".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:35 |
| S17 4 | 1 | "6037662".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:36 |
| S17 5 | 1 | "5887520".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:36 |
| S17 6 | 1 | "5887520".PN. | USPAT; USOCR | OR | ON | 2006/04/18 13:36 |

EAST Search History

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| S17 8 | 297 | @ad<="20031230" and (stress or strain) with (buffer or relax\$5 or relieve) same (ball or bump) same pad | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 14:01 |
| S18 0 | 350 | @ad<="20031230" and (stress or strain) with (buffer or relax\$5 or relieve or compliant) same (ball or bump) same pad | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 14:42 |
| S18 1 | 1 | "5550407".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:06 |
| S18 2 | 1 | "5834844".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:06 |
| S18 3 | 1 | "5886415".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:06 |
| S18 4 | 1 | "6111311".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:06 |
| S18 5 | 1 | "6111317".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:07 |
| S18 6 | 1 | "6153448".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:07 |
| S18 7 | 1 | "6181010".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:07 |
| S18 8 | 1 | "6181569".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:07 |
| S18 9 | 1 | "6184577".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:09 |
| S19 0 | 1 | "6255737".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:09 |
| S19 1 | 1 | "6313532".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:10 |
| S19 2 | 1 | "6674158".PN. | USPAT; USOCR | OR | ON | 2006/04/18 14:10 |
| S19 4 | 441 | @ad<="20031230" and (pad or electrode) with ("stress relaxation" or buffer or "stress relieve" or compliant) same bump | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 15:11 |
| S19 5 | 562 | @ad<="20031230" and "compliant pad" or "compliant bump" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 17:28 |
| S19 6 | 82 | @ad<="20031230" and "compliant bump" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 15:12 |

EAST Search History

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| S19 7 | 471 | @ad<="20031230" and "compliant pad" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 16:20 |
| S19 8 | 39 | @ad<="20031230" and "compliant pad" same stress | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 15:32 |
| S19 9 | 2 | ("5508228").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/04/18 16:20 |
| S20 0 | 1 | "6838368".PN. | USPAT; USOCR | OR | ON | 2006/04/18 17:25 |
| S20 1 | 1 | "6809020".PN. | USPAT; USOCR | OR | ON | 2006/04/18 17:26 |
| S20 2 | 1 | "6413845".PN. | USPAT; USOCR | OR | ON | 2006/04/18 17:27 |
| S20 3 | 1 | "6125043".PN. | USPAT; USOCR | OR | ON | 2006/04/18 17:27 |
| S20 4 | 1 | "4372809".PN. | USPAT; USOCR | OR | ON | 2006/04/18 17:27 |
| S20 5 | 598 | @ad<="20031230" and "compliant pad" or "compliant bump" or "compliant ball" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 17:28 |
| S20 6 | 566 | @ad<="20031230" and solder same pad same compliant | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 17:43 |
| S20 7 | 33 | @ad<="20031230" and solder same "bonding pad" same compliant | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 17:33 |
| S20 8 | 238 | @ad<="20031230" and solder same "bonding pad" same stress | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 17:33 |
| S20 9 | 65 | @ad<="20031230" and solder same "bonding pad" same buffer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 17:33 |

EAST Search History

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| S21 0 | 18 | @ad<="20031230" and solder same "bonding pad" same relief | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/30 10:24 |
| S21 1 | 7 | @ad<="20031230" and solder same "bonding pad" same relax\$5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 17:34 |
| S21 2 | 275 | @ad<="20031230" and solder same pad with compliant | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/18 17:43 |